TLIN2029A-Q1 Evaluation Module



ABSTRACT

The TLIN2029A-Q1 evaluation module (EVM) is described in this user's guide. This EVM helps designers evaluate device performance, support fast development, and analyze automotive local interconnect network (LIN) systems using TLIN2029A-Q1 and TLIN1029A-Q1 LIN physical layer transceiver devices.



Figure 1-1. TLIN2029EVM Board

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1 Introduction

1.1 Features

The EVM supports the following features:

- Commander Mode and Responder Mode configurations
- · Terminal block and header pins are available on all power and LIN bus connections
- · An optional VCC rail and pullup resistors for EN input and RXD (open-drain) output

1.2 Description

The TLIN2029EVM provides users with the ability to evaluate Ti's TLINx029A-Q1 family of single-channel, LIN transceivers. The EVM allows both commander and responder mode applications to be evaluated through the use of a single jumper that connects or disconnects the external 1-k Ω pullup resistor and series diode required in commander mode from the LIN bus.

The EVM has a low-voltage VCC rail that provides the voltage to the pullup resistors on the received data (RXD) open-drain output, and enable (EN) control input pins. The TLIN2029-Q1 supports a VIH from 2 V to 5.5 V, allowing operation with a variety of microcontrollers with common IO voltage levels such as 2.5 V, 3.3 V, and 5 V. Non-populated capacitor pads are available on the TXD and RXD pins to accommodate a variety of different tests requiring various capacitive load conditions.

The TLIN2029A-Q1 supports both 12 V and 24 V automotive applications and is operated with a supply voltage from 4 V to 48 V, plus an extended bus fault protection of ±60 V. Use the EVM to evaluate the TLIN1029A-Q1 device for 12-V automotive applications by replacing the TLIN2029A-Q1 with a TLIN1029A-Q1 transceiver.

Furthermore, the TLINx029A-Q1 transceivers include internally-protected bus terminals with greater than ±8-kV HBM and IEC ESD protection levels. If additional ESD protection is desired, a non-populated diode pad is available on the LIN bus to accommodate any SOD323 diode. Both headers and wire-terminals are provided on the power and LIN bus connections to allow the EVM to be evaluated in a larger system while still allowing for test equipment to be connected to the signals under test.

2 EVM Setup and Requirements

Use the following equipment to evaluate the performance of the TLIN2029A-Q1 device:

- Power supply capable of supplying the desired supply voltage. Typical LIN applications use 12 V or 24 V, but the TLIN2029A-Q1 will operate with any supply voltage from 4 V to 48 V. Connect this voltage across the VBAT and GND pins of either the TB1 or JMP3 connectors.
- Power supply capable of supplying the desired IO pin voltage from 2 V to 5.5 V. Connect this voltage across the VCC and GND pins of either the TB2 or JMP1 connectors.
- If the LIN bus interface is to be observed on an oscilloscope, use probes capable of tolerating voltages as large as VBAT.
- The logic interface pins (TXD, RXD, and EN) may interface to a microcontroller, pattern generator, or logic analyzer with logic levels matching the VCC voltage.

2.1 Commander Mode

To configure the board for commander mode, place a shunt on JMP4 to connect the external 1-k Ω resistor and series diode to the LIN bus per the LIN specification.

2.2 Responder Mode

To configure the board for responder mode, remove the shunt on JMP4 to disconnect the external 1-k Ω resistor and series diode from the LIN bus per the LIN specification.

www.ti.com Board Layout

3 Board Layout

The board layout uses two layers (top and bottom) with most of the routing placed on the top layer (see Figure 3-1 and Figure 3-2). The TLIN2029A-Q1 device has a flow through pinout with the logic interface pins on one side of the device and the LIN bus pins on the other side resulting in simple and straight forward routing of signal and power nets.

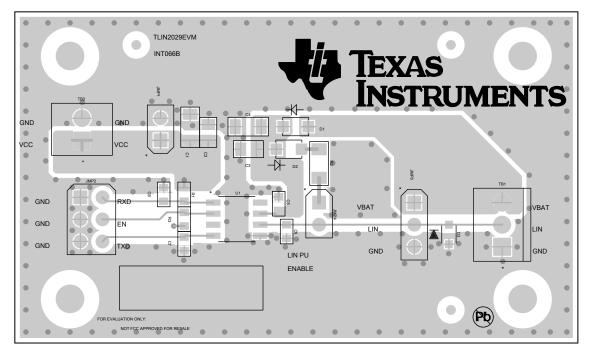
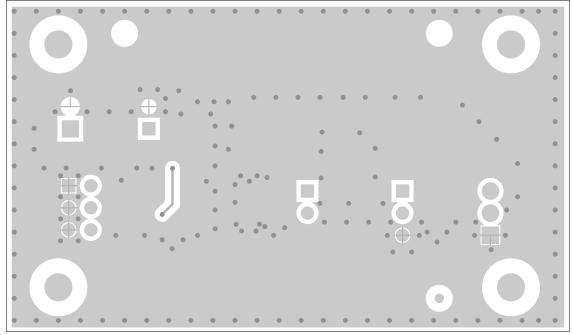


Figure 3-1. Top Layer



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Figure 3-2. Bottom Layer



4 Schematic and Bill of Materials

4.1 Schematic

Figure 4-1 illustrates the EVM schematic.

NOTES

- 1. Supply Voltage VBAT and VSUP: 4 V to 45 V
- 2. LIN Bus Input Voltage VLIN: 0 V to 36V
- 3. If used in Commander Mode, place a shunt on JMP4 and make sure VSUP < 36 V
- 4. VCC Voltage: 0 V to 5.25 V
- 5. VCC is only used to provide a voltage for the RXD and EN Pull Up resistors.

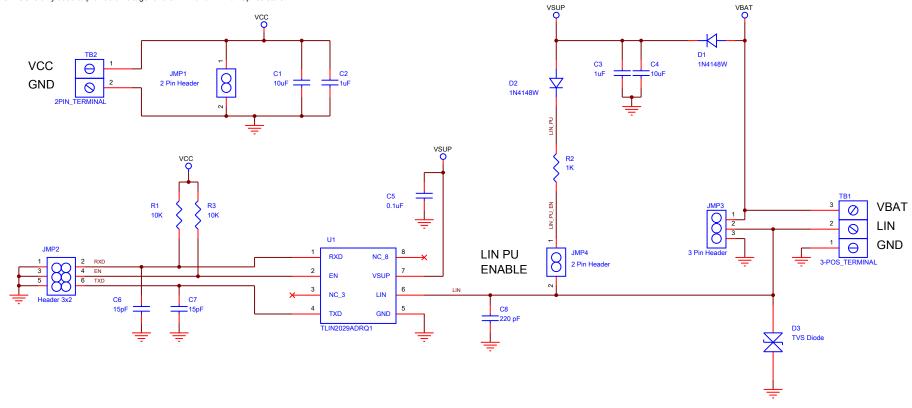


Figure 4-1. TLIN2029EVM Schematic

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4.2 Bill of Materials

Table 4-1 lists the EVM BOM.

Table 4-1. Bill of Materials

| Designator | QTY | Value | Description | Package Reference | Part Number | Manufacturer |
|-----------------------------------|-----|-----------------------|---|-----------------------------|--------------------|--|
| C1,C4 | 2 | 10 μF, 50 V | CAP, CERM, 10 μF, 50 V, ±10%, X5R, 1206 | 1206 | CL31A106KBHNNNE | Samsung Electro-Mechanics America, Inc. |
| C2,C3 | 2 | 1 μF, 50 V | CAP, CERM, 1 µF, 50 V, ±10%, X7R, 0805 | 0805 | CL21B105KBFNNNE | Samsung Electro-Mechanics America, Inc. |
| C5 | 1 | 0.1 μF, 50 V | CAP, CERM, 0.1 µF, 50 V, ±20%, X7R, 0603 | 0603 | C0603C104M5RACTU | Kemet |
| C6,C7 | 0 | 15 pF | CAP, CERM, 15 pF, 50 V, ±5%, C0G/NP0, 0603 | 0603 | CL10C150JB8NNNC | Samsung Electro-Mechanics America, Inc. |
| C8 | 1 | 220 pF | CAP, CERM, 220 pF, 50 V, ±1%, C0G/NP0, 0603 | 0603 | C0603C221F5GACTU | Kemet |
| D1,D2 | 2 | 1N4148W | Diode, General Purpose, 100 V, 150 mA, SOD123 | SOD123 | 1N4148W-TP | Micro Commercial Co |
| D3 | 0 | TVS Diode | Diode, Zener, 15 V / 24 V, 3 A, SOD323 | SOD323 | PESD1LIN,115 | Nexperia USA Inc. |
| FID1,FID2,FID3,F ID4,FID5,FID6 | 6 | Fiducial | Fiducial mark. There is nothing to buy or mount. | Fiducial | N/A | N/A |
| H1,H2,H3,H4 | 4 | NY PMS 440 0025 PH | Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead | Screw | NY PMS 440 0025 PH | B&F Fastener Supply |
| H5,H6,H7,H8 | 4 | 1902C | Standoff, Hex, 0.5"L #4-40 Nylon | Standoff | 1902C | Keystone |
| JMP1,JMP4 | 2 | 2 Pin Header | Header, 100mil, 2x1, Gold, TH | 2x1 Header | TSW-102-07-G-S | Samtec |
| JMP2 | 1 | Header 3x2 | Header, 100mil, 3x2, Gold, TH | 3x2 Header | TSW-103-07-G-D | Samtec |
| JMP3 | 1 | 3 Pin Header | Header, 100mil, 3x1, Gold, TH | 3x1 Header | TSW-103-07-G-S | Samtec |
| LB1 | 1 | PCB_Label | Thermal Transfer Printable labels, 0.650" W x 0.200" H - 10,000 per roll | PCB Label 0.650"H x 0.200"W | THT-14-423-10 | Brady |
| M1,M2,M3,M4 | 4 | MountingHole_125_NPTH | Mechanical mounting hole. There is nothing to buy or mount. | NPTH_125mil | N/A | N/A |
| PCB1 | 1 | PCB | Printed Circuit Board | PCB | INT066 | ANY |
| R1,R3 | 2 | 10K,1/4W,1% | RES, 10.0 k, 1%, 0.25 W, 0603 | 0603 | ESR03EZPF1002 | Rohm Semiconductor |
| R2 | 1 | 1K,1/4W,1% | RES, 1.00 k, 1%, 0.25 W, 1206 | 1206 | RC1206FR-071KL | Yageo |
| TB1 | 1 | 3-POS_TERMINAL | 3 Position Wire to Board Terminal Block Horizontal with Board 0.100" (2.54 mm) Through Hole | 2.54mm | 282834-3 | TE Connectivity AMP Connectors |
| TB2 | 1 | 2PIN_TERMINAL | 2 Position Wire to Board Terminal Block Horizontal with Board 0.100" (2.54 mm) Through Hole | 2.54mm | 282834-2 | TE Connectivity AMP Connectors |
| U1 | 1 | TLIN2029A-Q1 | Automotive Local Interconnect Network Transceiver, 8-SOIC | 8-SOIC | TLIN2029ADRQ1 | Texas Instruments |



Revision History Www.ti.com

5 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

| Cł | Changes from Revision * (October 2017) to Revision A (February 2022) | | | | |
|----|--|----------------|--|--|--|
| • | Updated the numbering format for tables, figures, and cross-references throughout the document | <mark>2</mark> | | | |
| | Changed all instances of legacy terminology to commander and responder where LIN is mentioned | | | | |

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